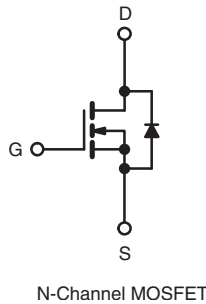
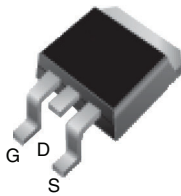


Power MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	600	
$R_{DS(on)}$ (Ω)	$V_{GS} = 10$ V	1.2
Q_g (Max.) (nC)	42	
Q_{gs} (nC)	10	
Q_{gd} (nC)	20	
Configuration	Single	

D²PAK (TO-263)



FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Low Gate Charge Q_g results in Simple Drive Requirement
- Improved Gate, Avalanche and Dynamic dV/dt Ruggedness
- Fully Characterized Capacitance and Avalanche Voltage and Current
- Effective C_{oss} Specified
- Compliant to RoHS Directive 2002/95/EC



Available
RoHS*
 COMPLIANT
 HALOGEN
FREE
 Available

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply
- High Speed Power Switching

TYPICAL SMPS TOPOLOGIES

- Single Transistor Forward

ORDERING INFORMATION			
Package	D ² PAK (TO-263)	D ² PAK (TO-263)	D ² PAK (TO-263)
Lead (Pb)-free and Halogen-free	SiHFBC40AS-GE3	SiHFBC40ASTRL-GE3 ^a	SiHFBC40ASTRR-GE3 ^a
Lead (Pb)-free	IRFBC40ASPbF	IRFBC40ASTRLPbF ^a	IRFBC40ASTRRPbF ^a
	SiHFBC40AS-E3	SiHFBC40ASTL-E3 ^a	SiHFBC40ASTR-E3 ^a
SnPb	IRFBC40AS	IRFBC40ASTRL ^a	IRFBC40ASTRR ^a
	SiHFBC40AS	SiHFBC40ASTL ^a	SiHFBC40ASTR ^a

Note

a. See device orientation.


ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)					
PARAMETER	SYMBOL		LIMIT	UNIT	
Drain-Source Voltage	V_{DS}		600	V	
Gate-Source Voltage	V_{GS}		± 30		
Continuous Drain Current ^e	V_{GS} at 10 V	$T_C = 25$ °C	6.2	A	
		$T_C = 100$ °C	3.9		
Pulsed Drain Current ^{a, e}	I_{DM}		25		
Linear Derating Factor			1.0	W/°C	
Single Pulse Avalanche Energy ^b	E_{AS}		570	mJ	
Repetitive Avalanche Current ^a	I_{AR}		6.2	A	
Repetitive Avalanche Energy ^a	E_{AR}		13	mJ	
Maximum Power Dissipation	$T_C = 25$ °C		P_D	125	W
Peak Diode Recovery dV/dt ^{c, e}	dV/dt		6.0	V/ns	
Operating Junction and Storage Temperature Range	T_J, T_{stg}		- 55 to + 150	°C	
Soldering Recommendations (Peak Temperature)	for 10 s		300 ^d		

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- Starting $T_J = 25$ °C, $L = 29.6$ mH, $R_g = 25$ Ω , $I_{AS} = 6.2$ A (see fig. 12).
- $I_{SD} \leq 6.2$ A, $dI/dt \leq 88$ A/ μ s, $V_{DD} \leq V_{DS}$, $T_J \leq 150$ °C.
- 1.6 mm from case.
- Uses IRFBC40A/SiHFBC40A data and test conditions.

* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	40	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	1.0	

SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	600	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}$, $I_D = 1\text{ mA}^d$	-	0.66	-	V/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2.0	-	4.0	V
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 30\text{ V}$	-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 600\text{ V}, V_{GS} = 0\text{ V}$	-	-	25	μA
		$V_{DS} = 480\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$	-	-	250	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 3.7\text{ A}^b$	-	-	1.2	Ω
Forward Transconductance	g_{fs}	$V_{DS} = 50\text{ V}, I_D = 3.7\text{ A}$	3.4	-	-	S
Dynamic						
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1.0\text{ MHz}$, see fig. 5	-	1036	-	pF
Output Capacitance	C_{oss}		-	136	-	
Reverse Transfer Capacitance	C_{rss}		-	7.0	-	
Output Capacitance	C_{oss}	$V_{GS} = 0\text{ V}$	$V_{DS} = 1.0\text{ V}, f = 1.0\text{ MHz}$	-	1487	-
			$V_{DS} = 480\text{ V}, f = 1.0\text{ MHz}$	-	36	-
Output Capacitance Effective	$C_{oss\text{ eff.}}$	$V_{DS} = 0\text{ V to } 480\text{ V}^c$	-	48	-	
Total Gate Charge	Q_g	$V_{GS} = 10\text{ V}, I_D = 6.2\text{ A}, V_{DS} = 480\text{ V}$, see fig. 6 and 13 ^b	-	-	42	nC
Gate-Source Charge	Q_{gs}		-	-	10	
Gate-Drain Charge	Q_{gd}		-	-	20	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 300\text{ V}, I_D = 6.2\text{ A}, R_g = 9.1\text{ }\Omega, R_D = 47\text{ }\Omega$, see fig. 10 ^b	-	13	-	ns
Rise Time	t_r		-	23	-	
Turn-Off Delay Time	$t_{d(off)}$		-	31	-	
Fall Time	t_f		-	18	-	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	6.2	A
Pulsed Diode Forward Current ^a	I_{SM}		-	-	25	
Body Diode Voltage	V_{SD}	$T_J = 25\text{ }^\circ\text{C}, I_S = 6.2\text{ A}, V_{GS} = 0\text{ V}^b$	-	-	1.5	V
Body Diode Reverse Recovery Time	t_{rr}	$T_J = 25\text{ }^\circ\text{C}, I_F = 6.2\text{ A}, di/dt = 100\text{ A}/\mu\text{s}^b$	-	431	647	ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	1.8	2.8	μC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)				

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$.
- c. $C_{oss\text{ eff.}}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DS} .
- d. Uses IRHFBC40A/SiHFBC40A data and test conditions.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

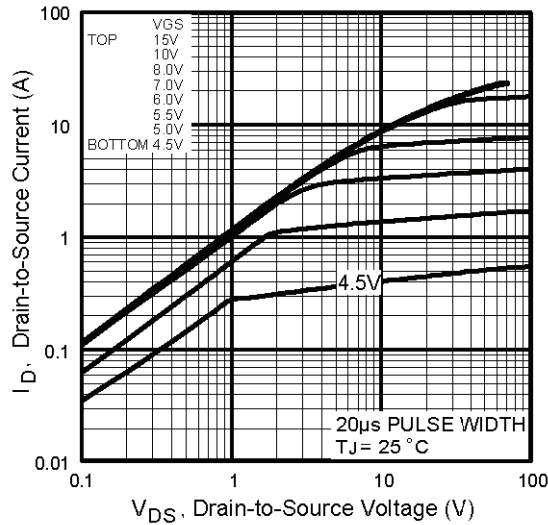


Fig. 1 - Typical Output Characteristics

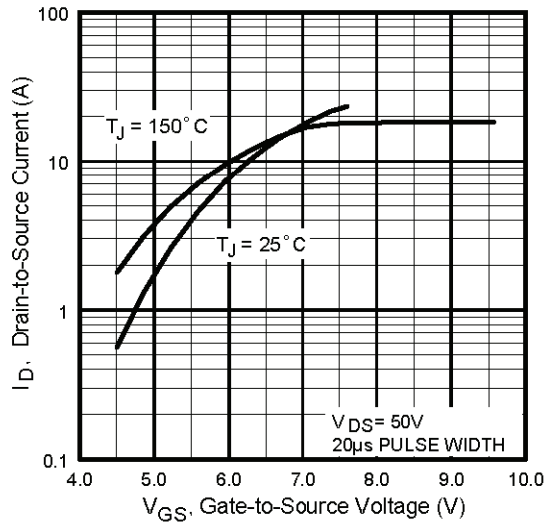


Fig. 3 - Typical Transfer Characteristics

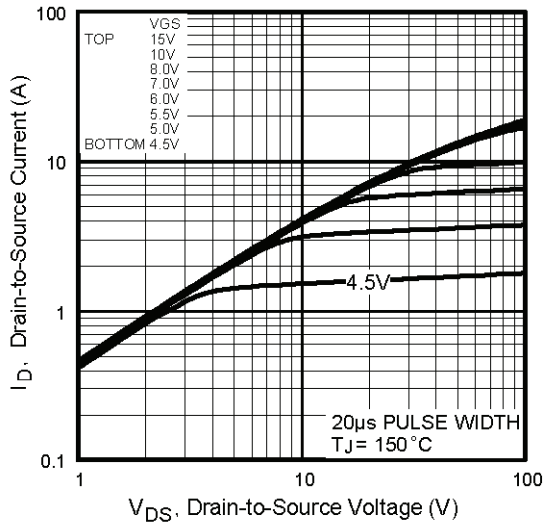


Fig. 2 - Typical Output Characteristics

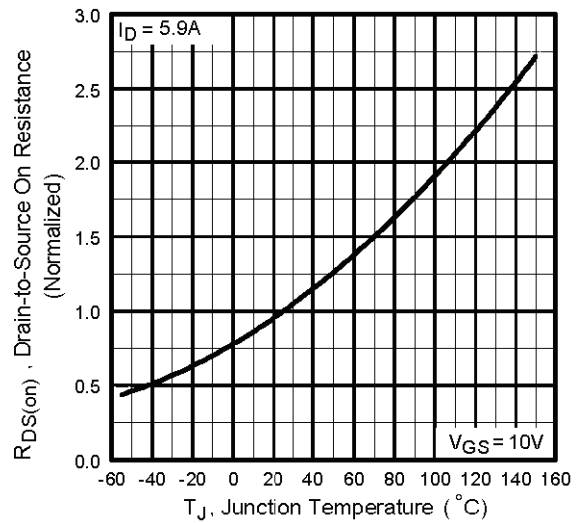


Fig. 4 - Normalized On-Resistance vs. Temperature

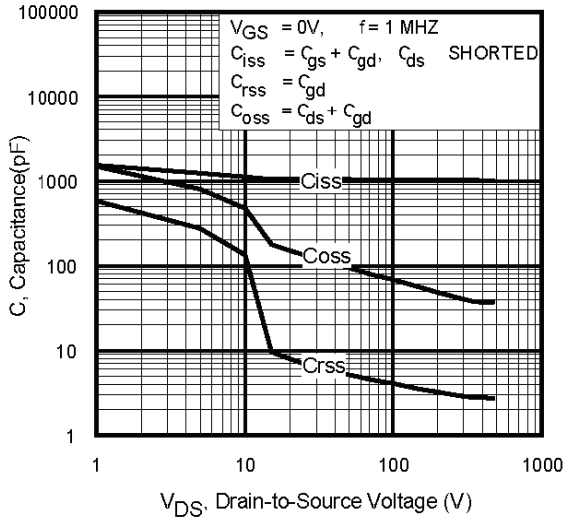


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

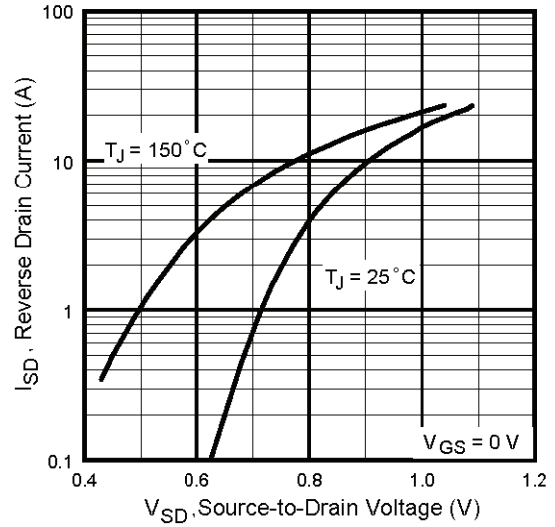


Fig. 7 - Typical Source-Drain Diode Forward Voltage

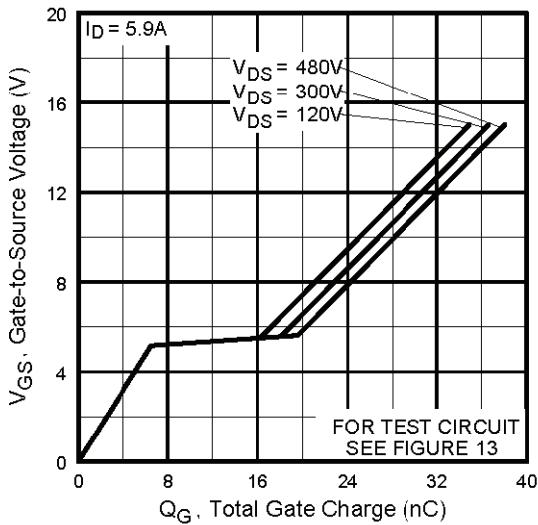


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

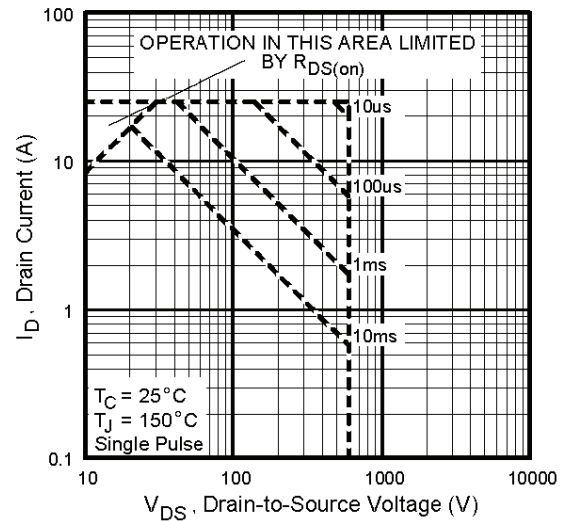


Fig. 8 - Maximum Safe Operating Area

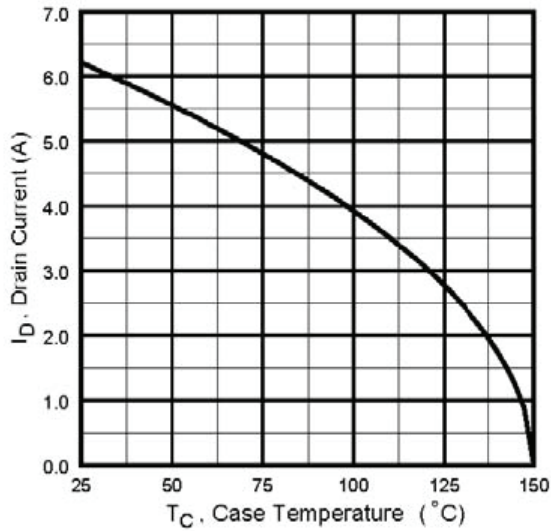


Fig. 9 - Maximum Drain Current vs. Case Temperature

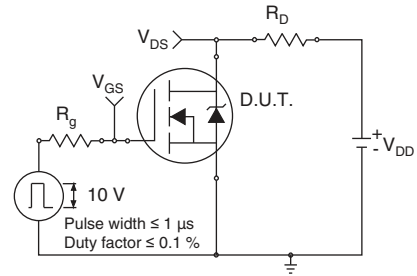


Fig. 10a - Switching Time Test Circuit

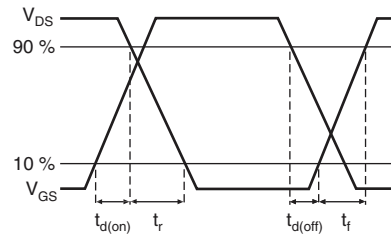


Fig. 10b - Switching Time Waveforms

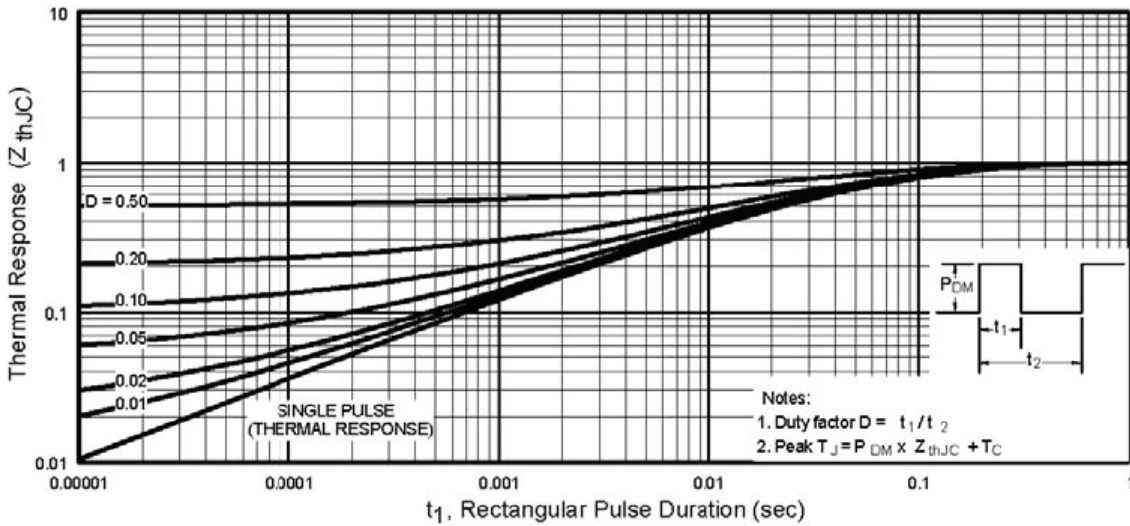


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

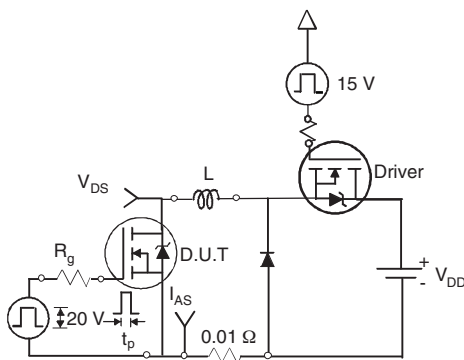


Fig. 12a - Unclamped Inductive Test Circuit

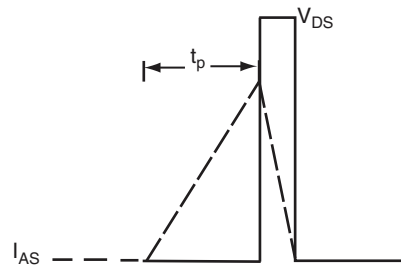


Fig. 12b - Unclamped Inductive Waveforms

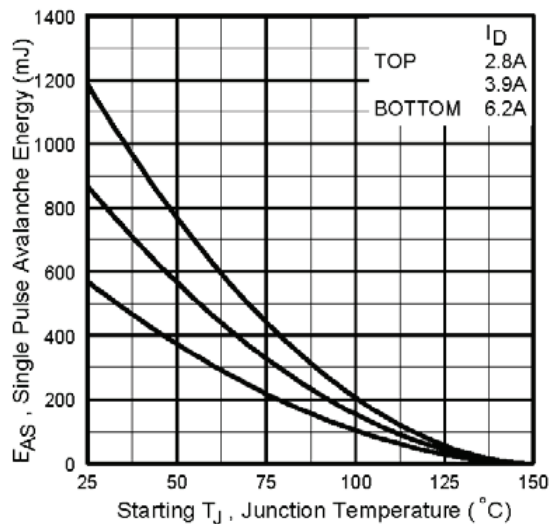


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

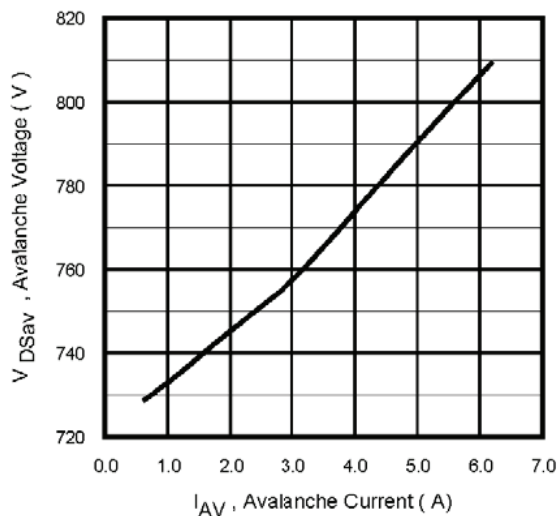


Fig. 12d - Maximum Avalanche Energy vs. Drain Current

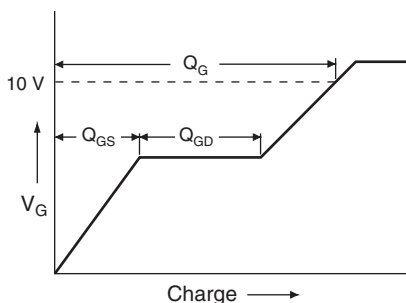


Fig. 13a - Basic Gate Charge Waveform

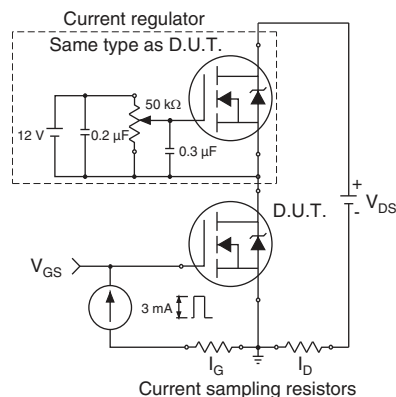
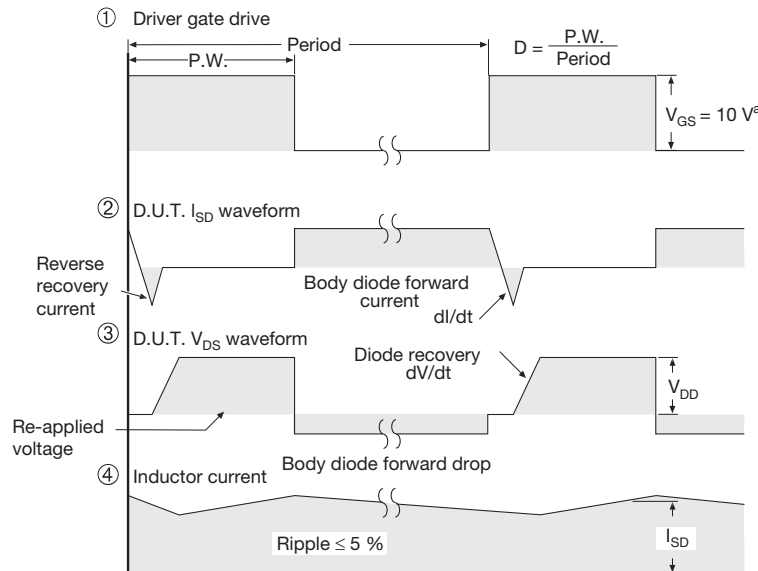


Fig. 13b - Gate Charge Test Circuit



Note

a. $V_{GS} = 5 V$ for logic level devices

Fig. 14 - For N-Channel

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